

Gemini Near Infrared Coronagraphic Imager  
Electronics System Document  
GEMINI SDN3001

MKIR# NICI -900-200-01  
Rev 0.1 (prerelease)  
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# 1 Gemini Near Infrared Coronagraphic Imager Electronics System Document

## 1.1 Overview

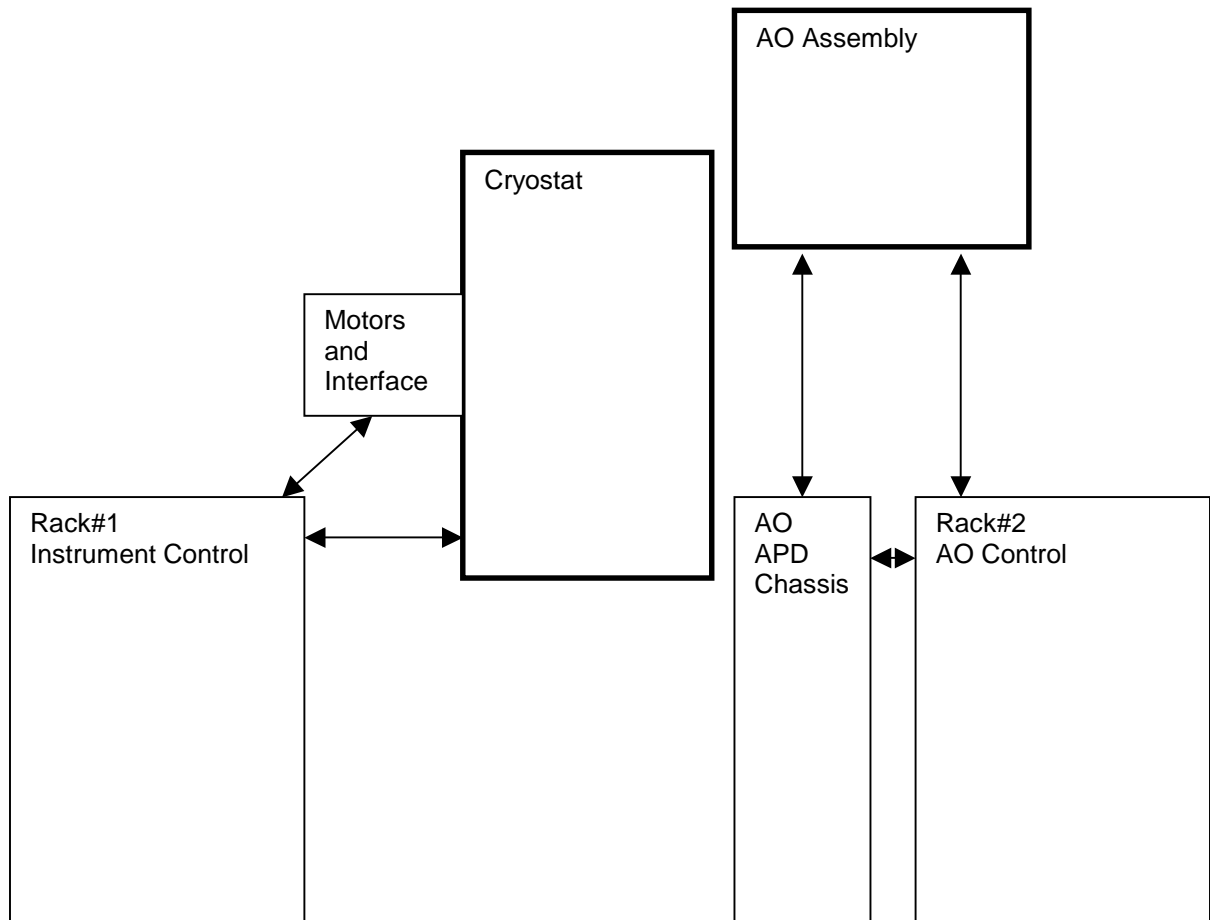
### 1.1.1 Purpose

This document details the electronics system level description for the Gemini Near Infrared Coronagraphic Imager, NICI. The document provides the highest level starting point for information regarding all electronics subsystems in NICI.

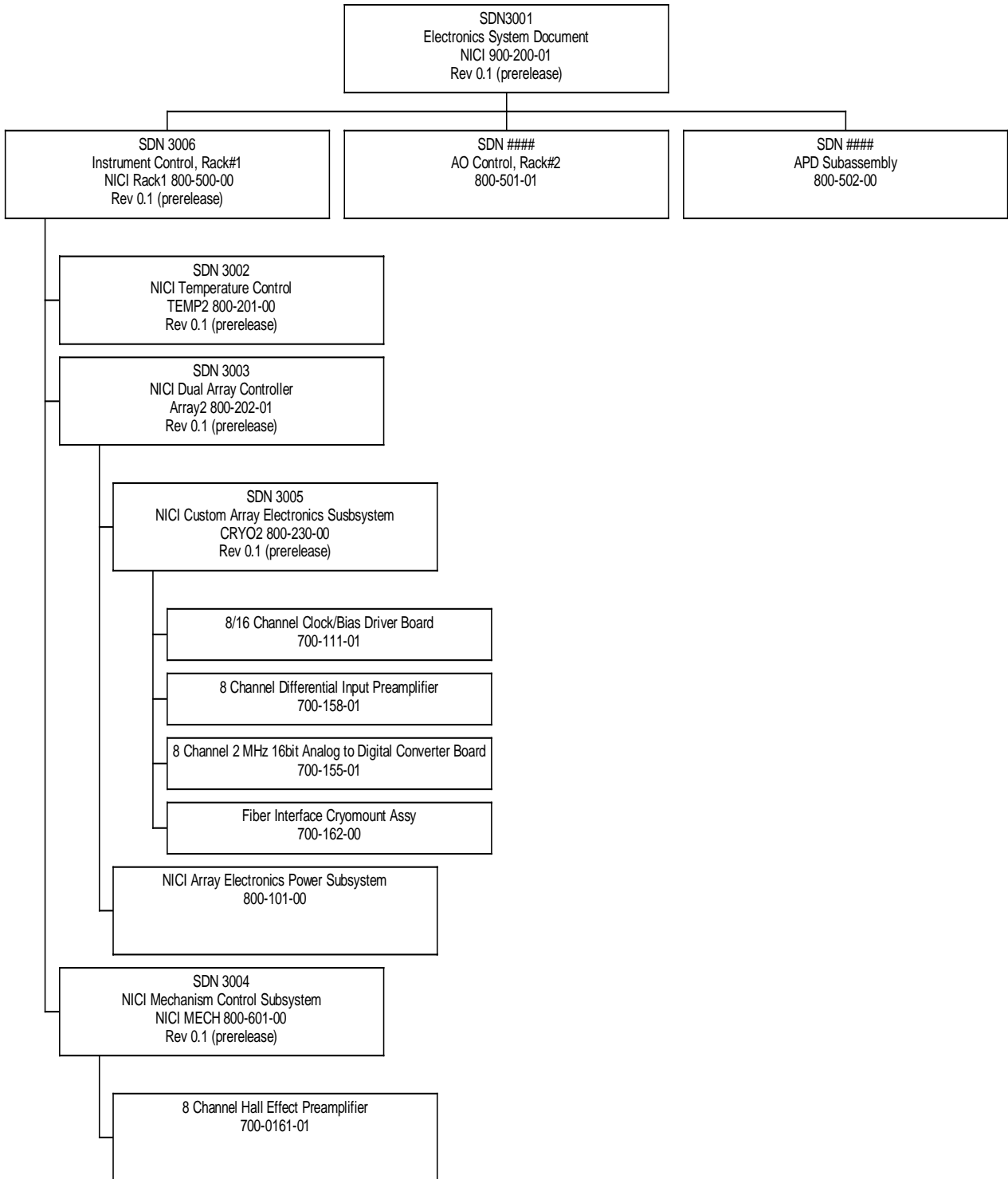
### 1.1.2 Major Assemblies

The major subsystems for NICI are physically located in two Gemini standard 1.3 meter cooled electronics racks, the AO assembly, AO APD chassis and cryostat mounted assemblies.

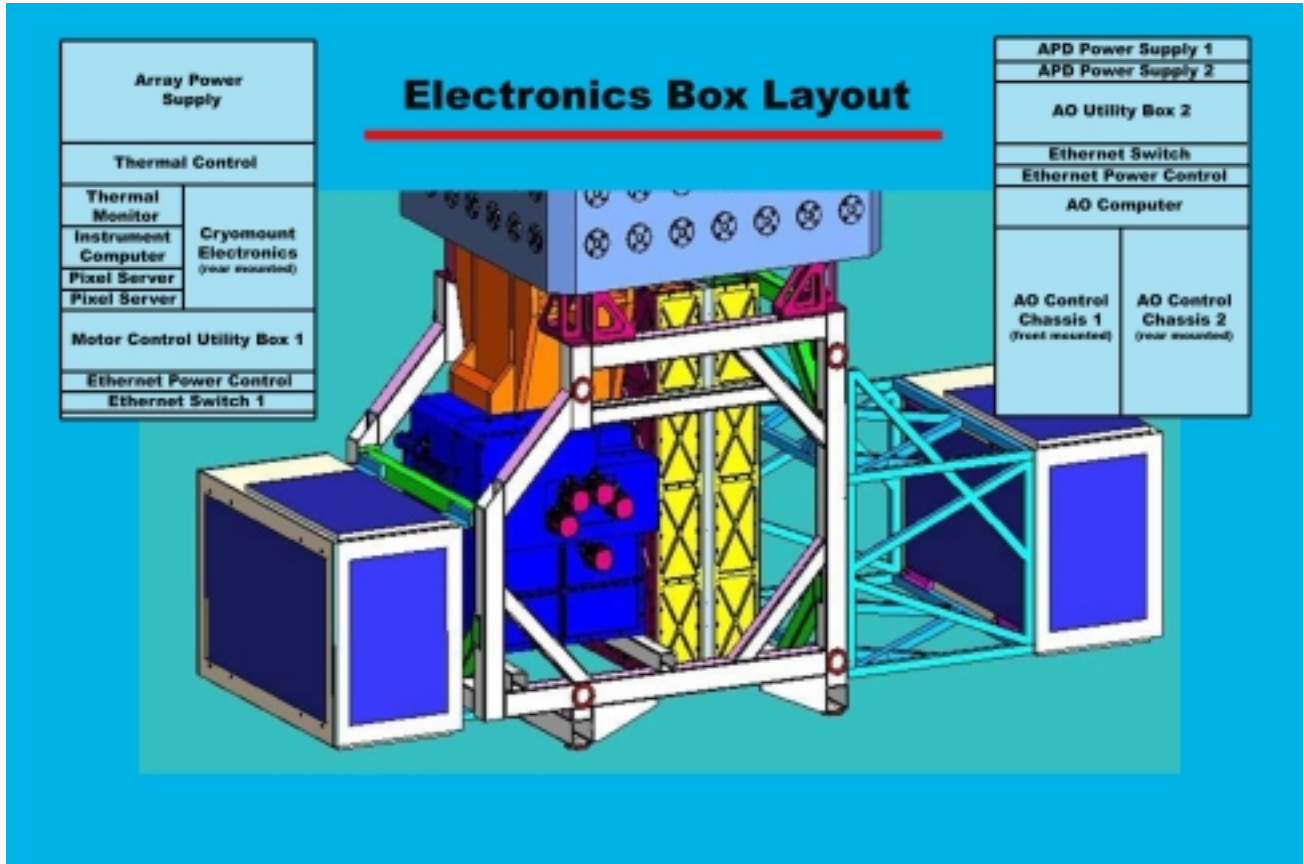
### 1.1.3 Block Diagram



### 1.1.4 Subsystem Document Tree



### 1.1.5 System Layout Diagram



### **1.1.6 System Power Totals**

The estimated electronics system total power dissipation is 2861 Watts.

## **1.2 Instrument Control, Rack#1**

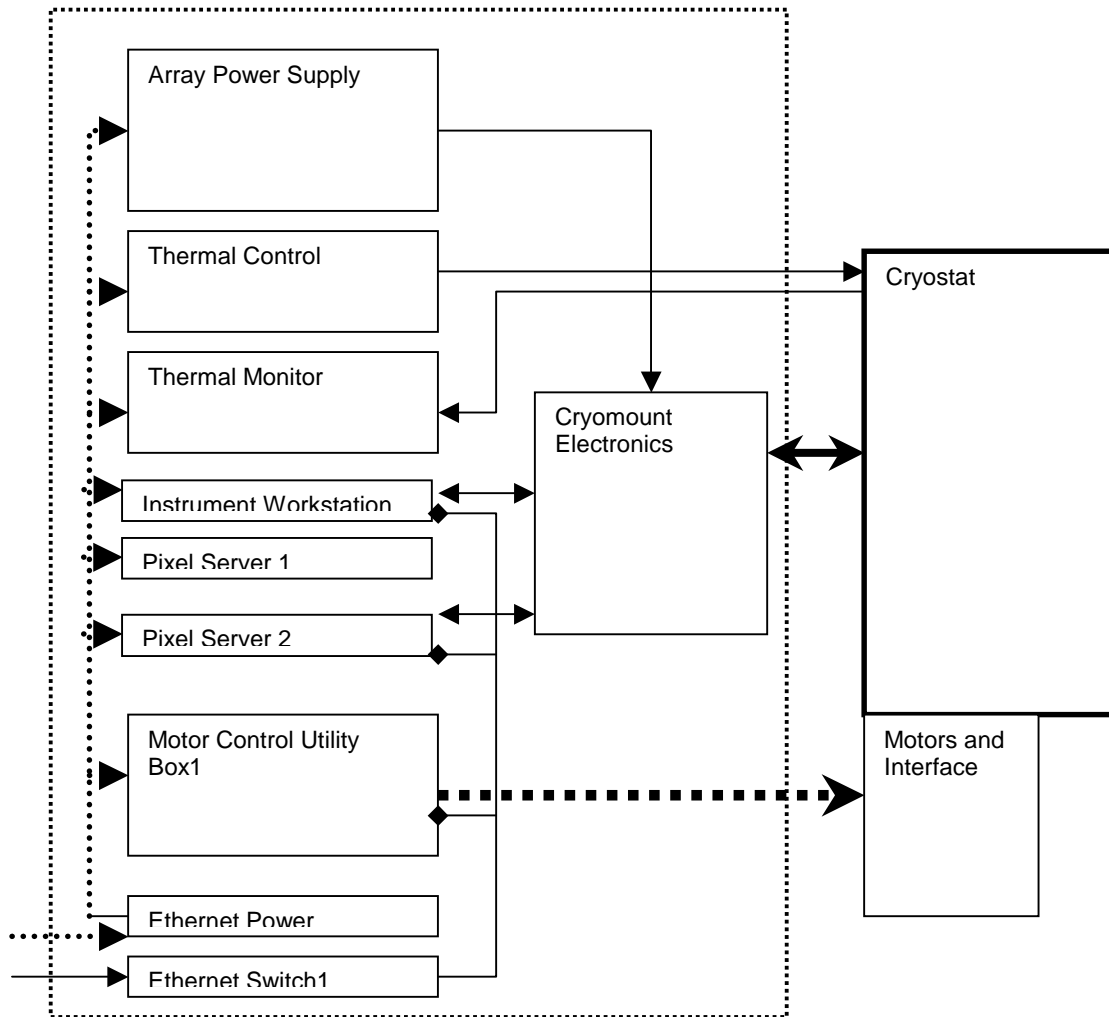
### **1.2.1 Functional Description**

Rack #1 houses the majority of the NICI camera and motor control electronics. The functions of the dual array drive and readout, cryogenic thermal control, monitoring and mechanism control are housed in major subsystems in this rack. Major interfaces are made to the cryostat and cryostat mounted motor systems.

### **1.2.2 Reference Documents**

NICI Instrument Control Rack#1 800-500-00

### 1.2.3 Block Diagram



### 1.2.4 Mechanical Dimensions

The 1.3 meter rack external dimensions.

External Height	Inches		Meters		External Width	Inches		Meters		External Depth	Inches		Meters		

The 1.3 meter rack internal dimensions.

Available front rack space	Inches		Meters		Available Width HP	Inches		Meters		Available Depth	Inches		Meters	
22.5U	31.50in	800.10mm			84	16.75in	425.45mm				31.50in	800.10mm		

## 1.2.5 Subassembly Mechanical Details

Assemblies										
Number	Subassembly Name	Manufacturer's Part	Height (in)	Height (mm)	U	Width (in)	Width (mm)	HP	Depth (in)	Depth (mm)
1	Instrument Workstation	Compaq Proliant DL360	1.65in	41.91mm	1	16.75in	425.45mm	84	16.75in	425.45mm
2	Pixel Server 1	Compaq Proliant DL360	1.65in	41.91mm	1	16.75in	425.45mm	84	16.75in	425.45mm
3	Pixel Server 2	Compaq Proliant DL360	1.65in	41.91mm	1	16.75in	425.45mm	84	16.75in	425.45mm
4	Array Power Supply	HP 66000	7.50in	190.50mm	5	16.75in	425.45mm	84	26.70in	678.18mm
5	Thermal Control	Lakeshore 332S X 2	3.50in	88.90mm	2	16.75in	425.45mm	84	22.75in	577.85mm
6	Thermal Monitor	Lakeshore 218	3.50in	88.90mm	2	16.75in	425.45mm	84	16.75in	425.45mm
7	Motor Control Utility Box1	Elma Type14 3U chassis	4.95in	125.73mm	3	16.75in	425.45mm	84	20.96in	532.38mm
8	Ethernet Power Control1	Baytech RPC3	1.65in	41.91mm	1	8.55in	217.17mm	43	5.25in	133.35mm
9	Ethernet Switch1	TBD	1.65in	41.91mm	1	16.75in	425.45mm	84	5.25in	133.35mm
10	Cryomount Electronics	MKIR	9.90in	251.46mm	6	16.75in	425.45mm	84	12.0in	304.80mm
				<b>Rack#1</b>	<b>24</b>					

1.2.6 Rack #1 subassembly physical positions

Rack #1 TOP DOWN LAYOUT					800.10mm available
Number	Subassembly Name	Manufacturer's Part	Height (in)	Height (mm)	U
<b>FRONT MOUNT</b>					
4	Array Power Supply	HP 66000	7.50in	190.50mm	5
5	Thermal Control	Lakeshore 332S X 2	3.50in	88.90mm	2
<b>COMBINED MOUNTING</b>					
<b>FRONT MOUNT</b>					
6	Thermal Monitor	Lakeshore 218	1.65in	41.91mm	1
1	Instrument Workstation	Compaq Proliant DL360	1.65in	41.91mm	1
2	Pixel Server 1	Compaq Proliant DL360	1.65in	41.91mm	1
3	Pixel Server 2	Compaq Proliant DL360	3.30in	83.82mm	1
<b>REAR MOUNT</b>					
10	Cryomount Electronics	MKIR	9.90in	251.46mm	6*
<b>FRONT MOUNT</b>					
7	Motor Control Utility Box1 Ethernet Power	Elma Type14 3U chassis	4.95in	125.73mm	3
8	Control1 Ethernet	Baytech RPC3	1.65in	41.91mm	1
9	Switch1	TBD	1.65in	41.91mm	1
front subtotal					18

### 1.2.7 Power Dissipation Estimates

See the supporting subsystem documents for a more detailed breakdown.

Subassembly Name	Power	Voltage input	Current input
Pixel Server 1	330.0W	120.0VAC	3.89A
Pixel Server 2	330.0W	120.0VAC	3.89A
Array Power Supply	91.8W	120.0VAC	.54A
Thermal Control	339.4W	120.0VAC	2.0A
Thermal Monitor	25.5W	120.0VAC	.15A
Motor Control Utility Box1	72.0W	120.0VAC	.85A
Ethernet Power Control1	5.0W	120.0VAC	.06A
Ethernet Switch1	5.0W	120.0VAC	.06A
<b>Total</b>	<b>1198.7W</b>		<b>11.43A</b>

### 1.2.8 Subassembly Weight Estimates

Subassembly Name	Weight (lbs)	Weight (kg)
Pixel Server 1	50.0lb	22.68kg
Pixel Server 2	50.0lb	22.68kg
Array Power Supply	69.0lb	31.30kg
Thermal Control	21.0lb	9.53kg
Thermal Monitor	6.6lb	2.99kg
Motor Control Utility Box1	30.0lb	13.61kg
Ethernet Power Control1	3.0lb	1.36kg
Ethernet Switch1	3.0lb	1.36kg
Cryomount Electronics	25.0lb	11.34kg
<b>TOTAL</b>	<b>257.60lb</b>	<b>116.85kg</b>

### 1.2.9 High Level Array Control System Functional Requirements

Must operate two 4 quadrant Aladdin type III style arrays  
*Reference Document:* SDN 3003 NICI Dual Array Controller

Must allow synchronization of readouts of the two arrays to 1 millisecond.

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*'Quick Answer':* The Clocking FPGA circuitry located on the FCRYO2 board will start exposures when in an ARM state and after receiving an optocoupled TTL level TRIGGER signal. Clocking will be synchronized to within 140nsec.

*Reference Document:* FCRYO2 700-2##-##

Single subarray mode minimum size 8x16 placed anywhere in the array and reflected to all four quadrants.

Global reset

Single sampled readout mode

Double correlated sampled readout mode

Multiple NDR noise reduction sampling mode

*'Quick Answer':* The Clocking FPGA circuitry located on the FCRYO2 board allows for flexible clocking encompassing these requirements. .

*Reference Document:* FCRYO2 700-2##-##

Connect to Gemini through a Socket for remote control

State set and state read commands

Populate the FITS header and ship the data to the DHS

Must operate in a standalone mode or under Gemini control in a remote mode

Must provide an image display in standalone mode

Must provide local storage for standalone mode

*Reference Document:* SDN 3003 NICI Dual Array Controller

Must time stamp frames using Gemini supplied time board\*

*'Quick Answer':* NICI will use a MKIR supplied time board located in the Pixel Servers

*Reference Document:* SDN 3003 NICI Dual Array Controller

Must have macro capability in stand alone mode

*Reference Document:* SDN 3003 NICI Dual Array Controller

## 1.2.10 High Level Array Control System Performance Requirements

Read noise - the controller should not increase the device noise by more than 10%

*'Quick Answer':* 'The gain is fixed at X5 and the bandwidth is limited to ~2.9Mhz with resulting calculated noise (with a 1K source impedance) is equal to 53.2uV. For the +/-2.5V input range of the ADCs' one bit (LSB) is equal to 76uV so the preamplifier contributes less than 1 LSB.'

*Reference Document:* PREAMP8 700-158-01

*'Quick Answer':* The previous generation array controllers using the same analog and ADC circuitry has been able to achieve the read noise requirement on 6 different Aladdin arrays on 3 different telescopes (SUBARU, IRTF, NRL/NO Flagstaff).

A/D resolution – adequate to get two bits on the noise

*'Quick Answer':* The gain is fixed at X5. From experience, the e/ADU ratio averages ~10e/ADU at this setting, leaving ~ 4bits of resolution on the noise from single Fowler pair readout of the Aladdin III.

*Reference Document:* PREAMP8 700-158-01

Full frame coadd rate - 2 Hz required (10 Hz goal)

Full frame to disk rate – 2 Hz required (10 Hz goal)

*'Quick Answer':* As of 3/15/2002, testing has shown data processing and storage rates have achieved the 2 Hz requirement and 10Hz goal for both coaddition and storage.

Display frame rate stand alone mode – .5 sec to display frame desired.

*'Quick Answer':* As of 3/15/2002, no testing has been performed.

## 1.3 AO Control, Rack#2

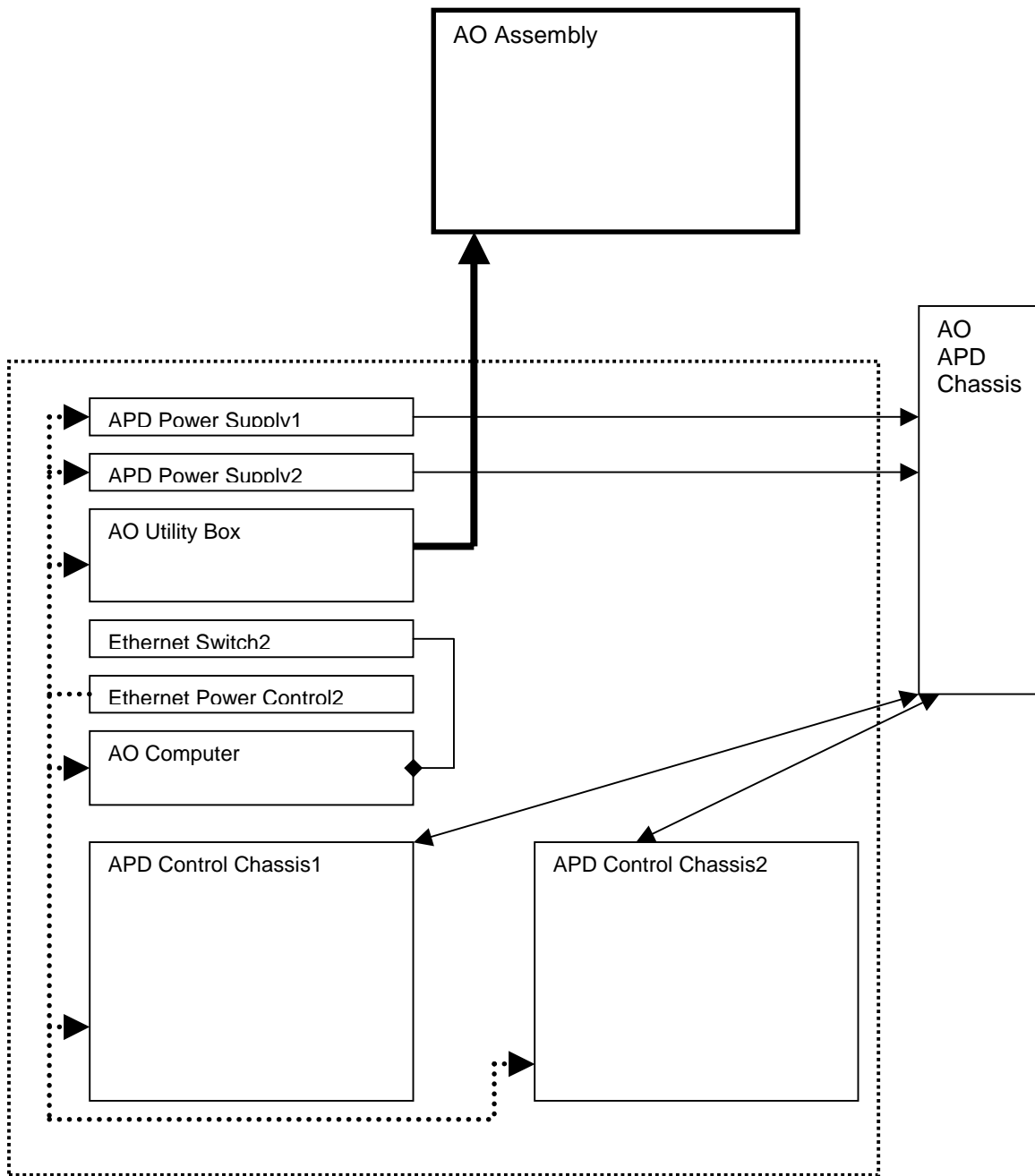
### 1.3.1 Functional Description

Rack #2 houses the majority of the AO control electronics. The functions of APD power supply , APD output counting, membrane and deformable mirror drive are housed in major subsystems in this rack. Major interfaces are made to the AO assembly and APD chassis.

### 1.3.2 Reference Documents

800-501-01 NICI Rack #2 Document

1.3.3 Block Diagram



### 1.3.4 Mechanical Dimensions

The 1.3 meter rack external dimensions.

External Height	Inches	Meters	External Width	Inches	Meters	External Depth	Inches	Meters
		1300mm						

The 1.3 meter rack internal dimensions.

Available front rack space	Inches	Meters	Available Width HP	Inches	Meters	Available Depth	Inches	Meters
22.5U	31.50in	800.10mm	84	16.75in	425.45mm	31.50in	800.10mm	

### 1.3.5 Subassembly Mechanical Details

Number	Subassembly Name	Manufacturer's Part	Height (in)	Height (mm)	U	Width (in)	Width (mm)	HP	Depth (in)	Depth (mm)
10	Ethernet Switch2	TBD	1.65in	41.91mm	1	16.75in	425.45mm	84	5.25in	133.35mm
11	Ethernet Power Control2	Baytech RPC3	1.65in	41.91mm	1	8.55in	217.17mm	43	5.25in	133.35mm
12	AO Computer	Dell Powedge 2550	3.30in	83.82mm	2	16.75in	425.45mm	84	16.75in	425.45mm
13	AO Utility Box	Elma Type14 23U chassis	4.95in	125.73mm	3	16.75in	425.45mm	84	20.96in	532.38mm
14	AO Control Chassis1	Elma Type12 8U chassis	14.0in	355.60mm	8	16.75in	425.45mm	84	19.60in	497.84mm
15	AO Control Chassis2	Elma Type12 8U chassis	14.0in	355.60mm	8	16.75in	425.45mm	84	19.60in	497.84mm
16	APD power Supply1	Sorenson DCS8-125E	1.65in	41.91mm	1	16.75in	425.45mm	84	19.0in	482.60mm
17	APD power Supply1	Sorenson DCS8-125E	1.65in	41.91mm	1	16.75in	425.45mm	84	19.0in	482.60mm

### 1.3.6 Rack #2 subassembly physical positions

#### Rack #2 TOP DOWN LAYOUT

Number	Subassembly Name	Manufacturer's Part	Height (in)	Height (mm)	U
<b>FRONT MOUNT</b>					
16	APD power Supply1	Sorenson DCS8-125E	1.65in	41.91mm	1
17	APD power Supply1	Sorenson DCS8-125E	1.65in	41.91mm	1
13	AO Utility Box2	Elma Type14 3U chassis	4.95in	125.73mm	3
10	Ethernet Switch2	TBD	1.65in	41.91mm	1
11	Ethernet Power Control2	Baytech RPC3	1.65in	41.91mm	1
subtotal					7

<b>COMBINED MOUNTING</b>					
<b>FRONT MOUNT</b>					
12	AO Computer	Dell Powedge 2550	3.30in	83.82mm	2
14	AO Control Chassis1	Elma Type12 8U chassis	14.0in	355.60mm	8
front subtotal					17
<b>REAR MOUNT</b>					
15	AO Control Chassis2	Elma Type12 8U chassis	14.0in	355.60mm	8

### 1.3.7 Power Dissipation Estimates

See the supporting subsystem documents for a more detailed breakdown.

Subassembly Name	Power	Voltage input	Current input
Ethernet Switch2	5.0W	120.0VAC	.06A
Ethernet Power Control2	5.0W	120.0VAC	.06A
AO Computer	330.0W	120.0VAC	3.89A
AO Utility Box2	72.0W	120.0VAC	.85A
AO Control Chassis1	200.0W	120.0VAC	2.36A
AO Control Chassis2	200.0W	120.0VAC	2.36A
APD power Supply1	90.0W	120.0VAC	.53A
APD power Supply1	90.0W	120.0VAC	.53A
<b>992.0W</b>			

### 1.3.8 Subassembly Weight Estimates

Subassembly Name	Weight (lbs)	Weight (kg)
Ethernet Switch2	3.0lb	1.36kg
Ethernet Power Control2	3.0lb	1.36kg
AO Computer	50.0lb	22.68kg
AO Utility Box2	30.0lb	13.61kg
AO Control Chassis1	25.0lb	11.34kg
AO Control Chassis2	25.0lb	11.34kg
APD power Supply1	19.0lb	8.62kg
APD power Supply1	19.0lb	8.62kg
<hr/> Ethernet Switch2	<hr/> 174.0lb	<hr/> 78.93kg
TOTAL	3.0lb	1.36kg

## 1.4 System Grounding

### 1.4.1 Plan Description

The grounding plan for the instrument is handled at five levels. The first is at the cryostat mounted electronics level. Separate analog and digital ground planes are used on all of the cryostat electronics boards and the backplane. A single point connection between them is unavoidably made at the analog to digital converters because the devices themselves are manufactured with an internal connection between the two potentials. The fact that there are multiple ADCs in the system places the best point for a single point ground at these connection points. This configuration dictates that the power supplies must have floating outputs. Previous experience has shown that there can also be substantial coupling capacitance between the power supply chassis and the outputs, so isolation is also often necessary.

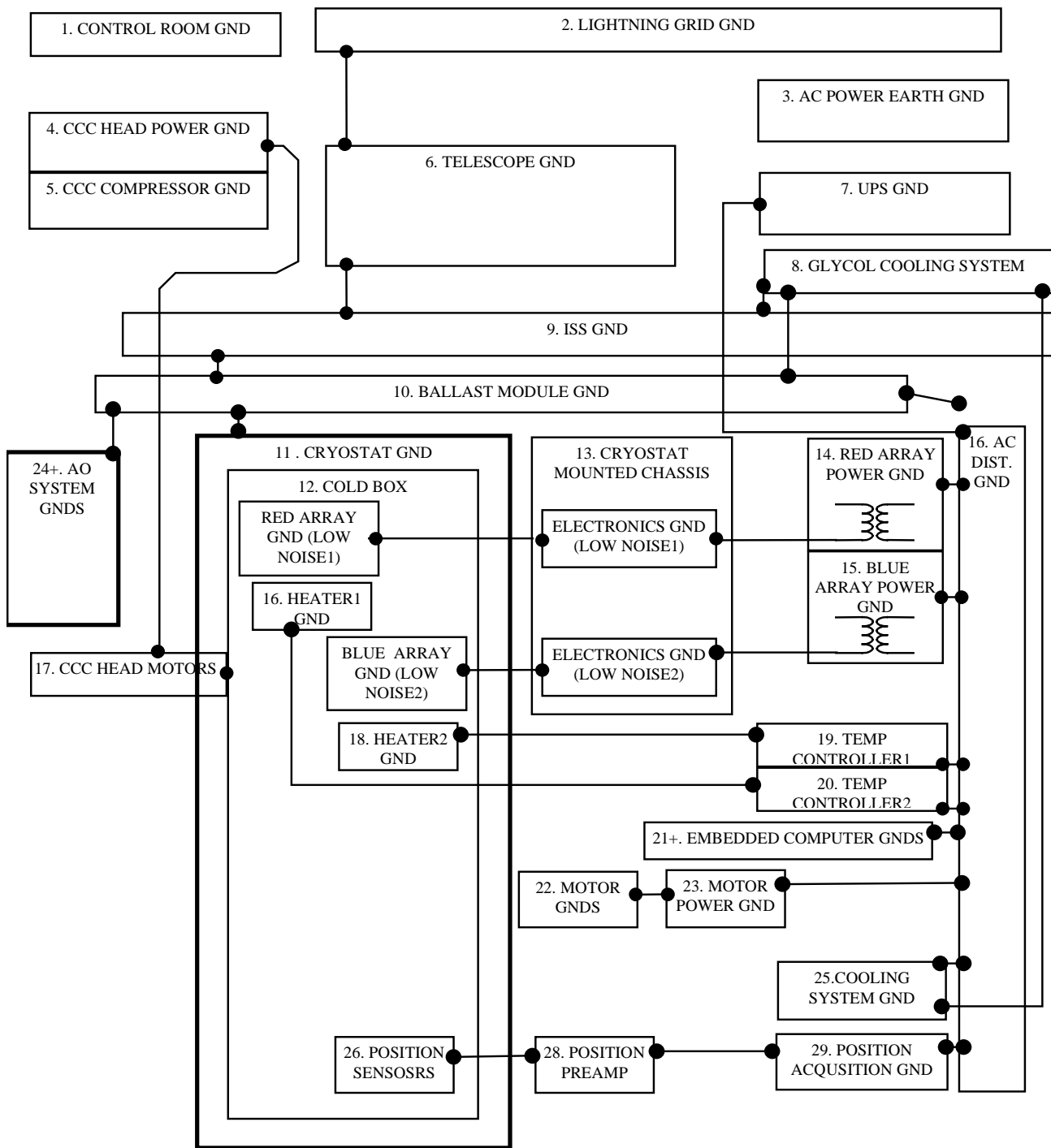
The second level of grounding is accomplished with the fiber optic link between the Embedded Computers (Instrument Workstation and Pixel Servers) and the cryostat mounted electronics. This complete optical isolation is intended to keep the high current and high frequency power distortion generated by the computer systems away from the low noise array electronics.

Each array electronics subsystem will have its own independent ground (that can be alternatively shorted to the other). This third level of grounding is intended to minimize crosstalk between the readout of the two arrays. The dual independent power supply systems support this configuration.

Another area of concern is the fourth level of ground isolation that between the closed cycle cooler system and the cryostat mounted electronics. The closed cycle cooler will not be electrically isolated from the cryostat vacuum jacket, so the two array wiring inside will be isolated.

The fifth level of the system grounding plan is illustrated in the following figure. It is an attempt to identify all of the different ground potential points in the facility that may affect the performance of the instrument. The diagram provides a starting point to identify and fix grounding problems.

1.4.2 System Ground Diagram



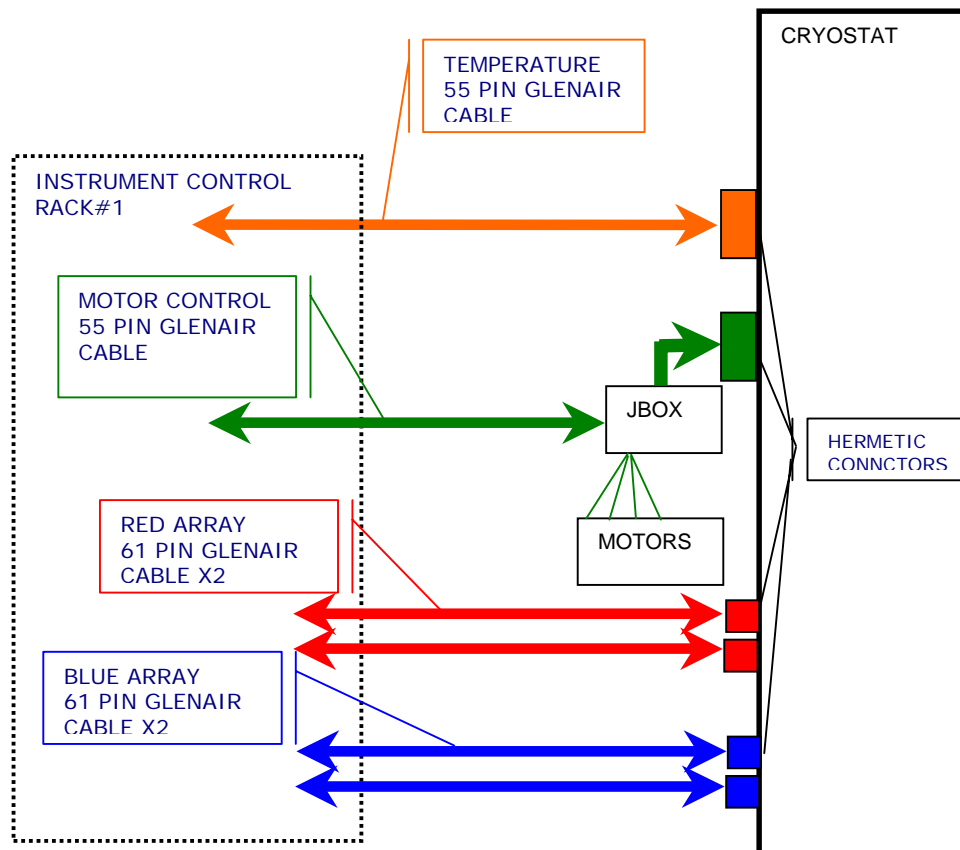
## 1.5 Connections and Cabling

### 1.5.1 Rack#1 to Cryostat External Cabling

Four types of connections are made between Rack#1 and the Cryostat Assembly. There are a total of 8 cables.

Type	Qty	Name	Manufacturer's Part	# conductors	Type of signals	Length	Connectors
1	1	Temperature Cable	Glenair 55pin	55	Low level/noise and heater power	15ft	cylindrical
2	1	Motor Control Cable	Glenair 55pin	55	Low level/noise and 48VDC	15ft	cylindrical
3	4	Array Cables	Glenair 61 pin ABC56145 rA	61	Critical Low noise	~3ft	cylindrical
4	2	CCC Power Supply	CTI or Custom	3	AC power	15ft?	cylindrical

### 1.5.2 Rack#1 cabling Diagram



### 1.5.3 Temperature cable

The temperature cable is a 55 pin, straight through (except for shield connection), molded cable assembly manufactured by Glenair. See the Appendix for the cable spreadsheet.

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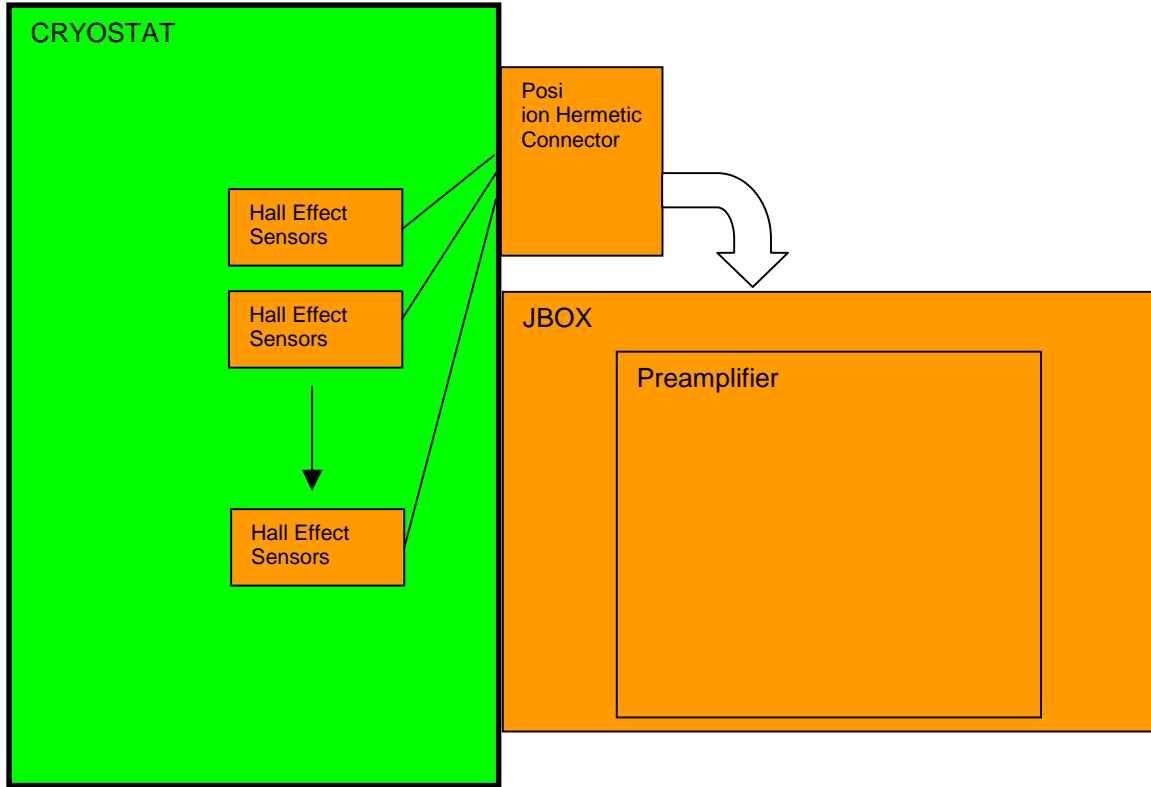
**1.5.4 Motor cable**

The motor cable is a 55 pin, straight through (except for shield connection), molded cable assembly manufactured by Glenair. See the Appendix for the cable spreadsheet.

**1.5.5 JBOX**

The Junction or JBOX provides the functions of:

1. Providing a convenient location to fanout the motor control and position signals to each motor.
2. Is the location for a magnetic Hall Effect sensor preamplifier.



**1.5.6 Array Cabling**

Connection to the arrays are made via Glenair custom 61 pin cables specifically designed for low noise, high shielding operation. See the Appendix for the spreadsheet of array signal mapping and connections.

ALLADIN 2 pinout (SB0152 ROIC CHANNEL OUTPUTS) socket Yamachi IC51-1244-410-1				700-150 Array Fanout			700-151 Config Bd J1,2,3,4=2mm P1,2=96 pin				xxx Thermal feedthrough			700-149 61 pin Bd J1,2=34 pin headers				600-010 61 pin CABLE conn=MS conn=MS3116-E				700-148 60 pin Bd J1,2=34 pin headers				Backplane		
pin num	signal name	high level	low level	signal	conn	pin	signal	conn	pin	signal	conn	pin	signal	conn	pin	signal	conn	pin	signal	conn	pin	signal	slot#	pin				
1	Q1_VGGCL	VDETCOM	-5	clk	q1_VGGCL	J1 1	VGGCL_T	J1 1	P1 A2,B2	VGGCL_T	JH1 2	4 3	VGGCL_T	J1 3	a 1	VGGCL_T	T-Q1&2	a	cond	VGGCL_T	a	1	J1 3	VGGCL_T	slot_7	C17		
2	Q1_VDDCL	-1.2	VDDUC	clk	q1_VDDCL	J1 3	VDDCL_T	J1 3	P1 A2,B27	VDDCL_T	JH2 2	20 19	VDDCL_T	J1 3	LL 1	shield	VDDCL_T	T-Q1&2	LL	cond	VDDCL_T	LL	1	J2 19	VDDCL_T	slot_7	C17	
3	Q1_VDDUC	-4.0 to -3.5		bias	q1_VDDUC	J1 5	VDDUC_T	J1 5	P1 C27	VDDUC_T	JH2 2	19 20	VDDUC_T	J2 20	KK 1	VDDUC_T	T-Q1&2	KK	cond	VDDUC_T	KK	1	J2 20	VDDUC_T	slot_7	C28		
4	Q1_PHS1	VpROW&COL	VnROW	clk	q1_PHS1	J1 7	P1 A28,B28	J1 7	P1 A28,B28	PSS_T	JH2 2	22 21	PSS_T	J2 21	AA 1	PSS_T	T-Q1&2	AA	shield	PSS_T	AA	1	J2 21	PSS_T	slot_7	C21		
5	Q1_PHS1	VpROW&COL	VnROW	clk	q1_PSI	J1 9	PS1_T	J1 9	P1 C28	PS1_T	JH2 2	22 21	PS1_T	J2 22	z 1	PS1_T	T-Q1&2	z	cond	PS1_T	z	1	J2 22	PS1_T	slot_1	C19		
6	Q1_PHS2	VpROW&COL	VnROW	clk	q1_PS2	J1 11	PS2_T	J1 11	P1 A29,B29	PS2_T	JH2 2	24 23	PS2_T	J2 23	i 1	PS2_T	T-Q1&2	i	shield	PS2_T	i	1	J2 23	PS2_T	slot_1	C21		
7	Q1_PHIROE	VpROW&COL	VnROW	clk	q1_PROE	J1 13	PROE_T	J1 13	P1 C29	PROE_T	JH2 2	23 24	PROE_T	J2 24	b 1	PROE_T	T-Q1&2	b	cond	PROE_T	b	1	J2 24	PROE_T	slot_1	C21		
8	Q1_PHIDES	VpROW&COL	VnROW	clk	q1_PDES	J1 15	PDES_T	J1 15	P1 A30,B30	PDES_T	JH2 2	26 25	PDES_T	J2 25	H 1	PDES_T	T-Q1&2	H	shield	PDES_T	H	1	J2 25	PDES_T	slot_1	C25		
9	Q1_PHS1	VpROW&COL	VnCOL	clk	q1_PFS	J1 17	PFS_T	J1 17	P1 C30	PFS_T	JH2 2	25 26	PFS_T	J2 26	G 1	PFS_T	T-Q1&2	G	cond	PFS_T	G	1	J2 26	PFS_T	slot_1	C27		
10	Q1_PHS1	VpROW&COL	VnCOL	clk	q1_PFI	J1 19	PF1_T	J1 19	P1 A31,B31	PF1_T	JH2 2	28 27	PF1_T	J2 27	K 1	PF1_T	T-Q1&2	K	shield	PF1_T	K	1	J2 27	PF1_T	slot_1	C29		
11	Q1_PHS2	VpROW&COL	VnCOL	clk	q1_PFI2	J1 21	PF2_T	J1 21	P1 C31	PF2_T	JH2 2	27 28	PF2_T	J2 28	J 1	PF2_T	T-Q1&2	J	cond	PF2_T	J	1	J2 28	PF2_T	slot_1	C31		
12	Q1_VnROW	-6.0 to -5.6	bias		q1_VNROW	J1 23	VNROW_T	J1 23	P1 A32,B32	VNROW_T	JH2 2	30 29	VNROW_T	J2 29	k 1	VNROW_T	T-Q1&2	k	shield	VNROW_T	k	1	J2 29	VNROW_T	slot_7	C30		
13	Q1_VnCOL	-6.0 to -3.5	bias		q1_VNCOL	J1 25	VNCOL_T	J1 25	P1 C32	VNCOL_T	JH2 2	29 30	VNCOL_T	J2 30	l 1	VNCOL_T	T-Q1&2	l	cond	VNCOL_T	l	1	J2 30	VNCOL_T	slot_7	C29		
14	Q1_Vp	0.0 to -0.5	bias		q1_Vp	J1 27	VP_T	J1 27	P1 A1,B1	VP_T	JH1 2	2 1	VP_T	J1 1	Z 1	VP_T	T-Q1&2	Z	cond	VP_T	Z	1	J1 1	VP_T	AGND1	A125?		
15	VSS	0	bias		q1_VSSCM	J1 29	VSSCM_T	J1 29	P1 C2	VSSCM_T	JH1 2	3 4	VSSCM_T	J2 4	z 1	VSSCM_T	T-Q1&2	z	shield	VSSCM_T	z	1	J1 4	VSSCM_T	AGND7	A22?		
16	VSUB	0 gnd	bias		AGND	J1 31	AGND	J1 31	P1 C1	AGND_T	JH1 2	1 2	AGND_T	J1 2	Y 1	AGND_T	T-Q1&2	Y	shield	AGND_T	Y	1	J1 2	AGND_T	AGND2	A25?		
17	VSS	0	bias		q3_VSSCM	J1 33	VSSCM_B	J1 33	P2 C2	VSSCM_B	JH1 2	3 4	VSSCM_B	J1 4	u 2	VSSCM_B	B-Q3&4	u	shield	VSSCM_B	u	2	J1 4	VSSCM_B	AGND6	A125?		
18	Q3_Vp	0.0 to -0.5	bias		VP_B	J1 35	VP_B	J1 35	P2 A1,B1	VP_B	JH1 2	1 2	VP_B	J1 2	Y 2	VP_B	B-Q3&4	Y	Y	VP_B	Y	2	J1 2	VP_B	AGND4	A25?		
19	Q3_VnCOL	-6.0 to -3.5	bias		q3_VNCOL	J1 37	VNCOL_B	J1 37	P2 C32	VNCOL_B	JH2 2	29 30	VNCOL_B	J2 30	i 2	VNCOL_B	B-Q3&4	i	cond	VNCOL_B	i	2	J2 30	VNCOL_B	slot_14	C30		
20	Q3_VnROW	-6.0 to -5.6	bias		q3_VNROW	J1 39	VNROW_B	J1 39	P2 A32,B32	VNROW_B	JH2 2	30 29	VNROW_B	J2 29	k 2	VNROW_B	B-Q3&4	k	shield	VNROW_B	k	2	J2 29	VNROW_B	slot_14	C30		
21	Q3_PHS2	VpROW&COL	VnCOL	clk	q3_PFI2	J1 41	PF2_B	J1 41	P2 C31	PF2_B	JH2 2	27 28	PF2_B	J2 28	J 2	PF2_B	B-Q3&4	J	cond	PF2_B	J	2	J2 28	PF2_B	slot_8	C31		
22	Q3_PHS1	VpROW&COL	VnCOL	clk	q3_PFI	J1 43	PF1_B	J1 43	P2 A31,B31	PF1_B	JH2 2	28 27	PF1_B	J2 27	K 2	PF1_B	B-Q3&4	K	shield	PF1_B	K	2	J2 27	PF1_B	slot_8	C29		
23	Q3_PHS1	VpROW&COL	VnCOL	clk	q3_PFS	J1 45	PFS_B	J1 45	P2 C30	PFS_B	JH2 2	25 26	PFS_B	J2 26	G 2	PFS_B	B-Q3&4	G	cond	PFS_B	G	2	J2 26	PFS_B	slot_8	C27		
24	Q3_PHS2	VpROW&COL	VnROW	clk	q3_PDES	J1 47	PDES_B	J1 47	P2 A30,B30	PDES_B	JH2 2	26 25	PDES_B	J2 25	H 2	PDES_B	B-Q3&4	H	shield	PDES_B	H	2	J2 25	PDES_B	slot_8	C25		
25	Q3_PHIROE	VpROW&COL	VnROW	clk	q3_PROE	J1 49	PROE_B	J1 49	P2 A29,B29	PROE_B	JH2 2	24 23	PROE_B	J2 24	b 2	PROE_B	B-Q3&4	b	cond	PROE_B	b	2	J2 24	PROE_B	slot_8	C21		
26	Q3_PHS2	VpROW&COL	VnROW	clk	q3_PS2	J1 51	PS2_B	J1 51	P2 A29,B29	PS2_B	JH2 2	24 23	PS2_B	J2 23	i 2	PS2_B	B-Q3&4	i	shield	PS2_B	i	2	J2 23	PS2_B	slot_8	C21		
27	Q3_PHS1	VpROW&COL	VnROW	clk	q3_PSI	J1 53	PS1_B	J1 53	P2 C28	PS1_B	JH2 2	21 22	PS1_B	J2 22	z 2	PS1_B	B-Q3&4	z	cond	PS1_B	z	2	J2 22	PS1_B	slot_8	C19		
28	Q3_PHS2	VpROW&COL	VnROW	clk	q3_PSS	J1 55	PSS_B	J1 55	P2 A28,B28	PSS_B	JH2 2	22 21	PSS_B	J2 21	AA 2	PSS_B	B-Q3&4	AA	shield	PSS_B	AA	2	J2 21	PSS_B	slot_14	C31		
29	Q3_VDDUC	-4.0 to -3.5	bias		q3_VDDUC	J1 57	VDDUC_B	J1 57	P2 C27	VDDUC_B	JH2 2	19 20	VDDUC_B	J2 20	KK 2	VDDUC_B	B-Q3&4	KK	cond	VDDUC_B	KK	2	J2 20	VDDUC_B	slot_14	C28		
30	Q3_VDDCL	-1.2	VDDUC	clk	q3_VDDCL	J1 59	VDDCL_B	J1 59	P2 A27,B27	VDDCL_B	JH2 2	20 19	VDDCL_B	J2 19	LL 2	VDDCL_B	B-Q3&4	LL	shield	VDDCL_B	LL	2	J2 19	VDDCL_B	slot_14	C17		
31	Q3_VGGCL	VDETCOM	-5	clk	q3_VGGCL	J1 60	VGGCL_B	J1 60	P2 A2,B2	VGGCL_B	JH1 2	4 3	VGGCL_B	J1 3	a 2	VGGCL_B	B-Q3&4	a	cond	VGGCL_B	a	2	J1 3	VGGCL_B	slot_14	C17		
32	Q3_TEND				q3_TEND	J2 1	Q3_TEND	J2 1	P2 C15	Q3_TEND	JH1 2	29 30	Q3_TEND	J1 30	nc 2	Q3_TEND				Q3_TEND	nc 2	J1 30	Q3_TEND					
33	Q3_VRSTG	-3.5	-5.6	clk	q3_VRSTG	J2 3	VRSTG_B	J2 3	P2 C3	VRSTG_B	JH1 2	5 6	VRSTG_B	J1 6	FF 2	VRSTG_B	B-Q3&4	FF	cond	VRSTG_B	FF 2	J1 6	VRSTG_B	slot_14	C23			
34	Q3_VROWOFF	0.0 to -0.7			q3_VROWOFF	J2 5	VROWOFF_B	J2 5	P2 A4,B4	VROWOFF_B	JH1 2	8 7	VROWOFF_B	J1 7	i 2	VROWOFF_B	B-Q3&4	i	shield	VROWOFF_B	i	2	J1 7	VROWOFF_B	AGND5	A22?		
35	Q3_IREF	-1.5 to -2.5		Isource	q3_IREF	J2 7	VREF_B	J2 7	P2 C4	VREF_B	JH1 2	7 8	VREF_B	J1 8	b 2	VREF_B	B-Q3&4	b	cond	VREF_B	b	2	J1 8	VREF_B	slot_14	C25		
36	Q3_VROWON	-6.0 to -5.6			q3_VROWON	J2 9	VROWON_B	J2 9	P2 A3,B3	VROWON_B	JH1 2	6 5	VROWON_B	J1 5	G 2	VROWON_B	B-Q3&4	G	shield	VROWON_B	G	2	J1 5	VROWON_B	slot_14	C19		
37	Q3_VRSTR	-3.5	-5.6	clk	q3_VRSTR	J2 11	VRSTR_B	J2 11	P2 A5,B5	VRSTR_B	JH1 2	10 9	VRSTR_B	J1 9	MM 2	VRSTR_B	B-Q3&4	MM	cond	VRSTR_B	MM	2	J1 9	VRSTR_B	slot_14	C21		
38	Q3_OUT1			output	q3_OUT1	J2 13	Q3OUT1+	J2 13	P2 C6	Q3OUT1+	JH1 2	11 12	Q3OUT1+	J1 12	DD 2	Q3OUT1+	B-Q3&4	DD	cond	Q3OUT1+	DD	2	J1 12	Q3OUT1+	slot_13	C3		
39	Q3_OUT2			output	q3_OUT2	J2 15	Q3OUT2+	J2 15	P2 C7	Q3OUT2+	JH1 2	13 14	Q3OUT2+	J1 14	W 2	Q3OUT2+	B-Q3&4	W	cond	Q3OUT2+	W	2	J1 14	Q3OUT2+	slot_13	C5		
40	Q3_OUT3			output	q3_OUT3	J2 17	Q3OUT3+	J2 17	P2 C8	Q3OUT3+	JH1 2	15 16	Q3OUT3+	J1 16	q 2	Q3OUT3+	B-Q3&4	q	cond	Q3OUT3+	q	2	J1 16	Q3OUT3+	slot_13	C7		
41	Q3_OUT4			output	q3_OUT4	J2 19	Q3OUT4+	J2 19	P2 C9	Q3OUT4+	JH1 2	17 18	Q3OUT4+	J1 18	U 2	Q3OUT4+	B-Q3&4	U	cond	Q3OUT4+	U	2	J1 18	Q3OUT4+	slot_13	C9		
42	Q3_OUT5			output	q3_OUT5	J2 21	Q3OUT5+	J2 21	P2 C10	Q3OUT5+	JH1 2	19 20	Q3OUT5+	J1 20	S 2	Q3OUT5+	B-Q3&4	S	cond	Q3OUT5+	S	2	J1 20	Q3OUT5+	slot_13	C11		
43	Q3_OUT6			output	q3_OUT6	J2 23	Q3OUT6+	J2 23	P2 C11	Q3OUT6+	JH1 2	21 22	Q3OUT6+	J1 22	n 2	Q3OUT6+	B-Q3&4	n	cond	Q3OUT6+	n	2	J1 22	Q3OUT6+	slot_13	C13		
44	Q3_OUT7			output	q3_OUT7	J2 25	Q3OUT7+	J2 25	P2 C12	Q3OUT7+	JH1 2	23 24	Q3OUT7+	J1 24	BB 2	Q3OUT7+	B-Q3&4	BB	cond	Q3OUT7+	BB	2	J1 24	Q3OUT7+	slot_13	C15		
45	Q3_OUT8			output	q3_OUT8	J2 27	Q3OUT8+	J2 27	P2 C13	Q3OUT8+	JH1 2	25 26	Q3OUT8+	J1 26	P 2	Q3OUT8+	B-Q3&4	P	cond	Q3OUT8+	P	2	J1 26	Q3OUT8+	slot_13	C17		
46	Q3_VDDOUT	-1.0 to -1.3	bias		q3_VDDOUT	J2 29	VDDOUT_B	J2 29	P2 C14	VDDOUT_B	JH1&2	27 1	28 2	VDDOUT_B	J1&2	26 2	N,A	B	c,s	VDDOUT_B	N,A	2	J1&2	28 2	VDDOUT_B	slot_14	C26	
47	Q3_VDETCOM	-2.8 to -3.4	bias		q3_VDETCOM	J2 31	VDETCOM_B	J2 31	P2 A18,B18	VDETCOM_B	JH2 2	2 1	2	VDETCOM_B	J2 1	B 2	VDETCOM_B	B-Q3&4	B	cond	VDETCOM_B	B	2	J2 1	VDETCOM_B	slot_14	C27	
48	Q4_VDDOUT	-1.0 to -1.3	bias		q3_VDDOUT	J2 33	VDDOUT_B	J2 33	P2 C19	Q4OUT8+	JH2 2	3 4	Q4OUT8+	J2 4	b 2	Q4OUT8+	B-Q3&4	b	cond									





TEMPERATURE CONTROL SUBSYSTEM

TEMPERATURE SENSORS AND HEATERS										TEMPERATURE CONTROL SUBSYSTEM													
FUNCTION	CRYO NUM	WIRE COLOR	LOGAL SIGNAL NAME	.1X1X10 TEMP 10PIN CGRID CONN	.1X1X10 TEMP 10CON CGRID CONN	7 INCH MANGANIN CABLE	NON-STD .1X2X5 16PIN HDR FEED-	.1X2X5 16PIN CON FEED-	7 INCH MANGANIN	.1X1X8 8PIN CGRID	.1X1X8 8CON CGRID	7 INCH MANGANIN	JH1 30 PIN IDC	55 PIN HERMETIC INTRF BD	55 PIN HERMETIC TEMP	TEMP 55 PIN CABLE	GLENAIR 55COND CABLE	GLENAIR 55COND	TEMP 55 PIN CABLE	TEMP 55 PIN	55 PIN INTRF BD	DIN6-REAR PNL RED LAKESHORE MODEL 331 SENSOR CONN	
RED ARRAY	RED_I+	BLK/BLU	I+	3	3		1	2		1	1		1	JH1-1	p	p			p	p	JH1-1	RED_I+	5 [H] CHNL A
TEMP SENSOR	RED_V+	YEL/CLR	V+	4	4		2	1		2	2		2	JH1-2	BB	BB			BB	BB	JH1-2	RED_V+	4 [V+] CHNL A
	RED_I-	RED	I-	5	5		3	4		3	3		3	JH1-3	q	q			q	q	JH1-3	RED_I-	1 [I-] CHNL A
	RED_V-	GRN	V-	6	6		4	3		4	4		4	JH1-4	v	v			v	v	JH1-4	RED_V-	2 [V-] CHNL A
RED ARRAY	RED_HTR1	R3 R4+		7	7		5	6		5	5		5	JH1-5	A	A			A	A	JH1-5	RED_HTR1	HI
HEATER	RED_HTR2	R3 R4-		8	8		6	5		6	6		6	JH1-6	W	W			W	W	JH1-6	RED_HTR2	LO
RESISTORS	RED_HTR3	R1 R2+		9	9		7	7		7	7		7	JH1-7	X	X			X	X	JH1-7	RED_HTR3	GND
	RED_HTR4	K1 R2-		10	10		8	7		8	8		8	JH1-8	B	B			B	B	JH1-8	RED_HTR4	
BLUE ARRAY	BLU_I+	BLK/BLU	I+	3	3		1	2		1	1		9	JH1-9	Y	Y			Y	Y	JH1-9	BLU_I+	5 [H] CHNL A
TEMP SENSOR	BLU_V+	YEL/CLR	V+	4	4		2	1		2	2		10	JH1-10	C	C			C	C	JH1-10	BLU_V+	4 [V+] CHNL A
	BLU_I-	RED	I-	5	5		3	4		3	3		11	JH1-11	CC	CC			CC	CC	JH1-11	BLU_I-	1 [I-] CHNL A
	BLU_V-	GRN	V-	6	6		4	3		4	4		12	JH1-12	r	r			r	r	JH1-12	BLU_V-	2 [V-] CHNL A
BLUE ARRAY	BLU_HTR1	R3 R4+		7	7		5	6		5	5		13	JH1-13	Z	Z			Z	Z	JH1-13	BLU_HTR1	HI
HEATER	BLU_HTR2	R3 R4-		8	8		6	5		6	6		14	JH1-14	D	D			D	D	JH1-14	BLU_HTR2	LO
RESISTORS	BLU_HTR3	R1 R2+		9	9		7	7		7	7		15	JH1-15	E	E			E	E	JH1-15	BLU_HTR3	GND
	BLU_HTR4	K1 R2-		10	10		8	7		8	8		16	JH1-16	S	S			S	S	JH1-16	BLU_HTR4	
CCC 1ST STG	STG1_TMP	BLK/BLU	I+	1	1								17	JH1-17	F	F			F	F	JH1-17	STG1_I+	IN1+
TEMP SENSOR	STG1_TMP	YEL/CLR	V+	2	2								18	JH1-18	a	a			a	a	JH1-18	STG1_V+	IN1V+
	STG1_TMP	RED	I-	3	3								19	JH1-19	b	b			b	b	JH1-19	STG1_I-	IN1I-
	STG1_TMP	GRN	V-	4	4								20	JH1-20	t	t			t	t	JH1-20	STG1_V-	IN1V-
CCC 2ND STG	STG2_TMP	BLK/BLU	I+	1	1								21	JH1-21	G	G			G	G	JH1-21	STG2_I+	IN2+
TEMP SENSOR	STG2_TMP	YEL/CLR	V+	2	2								22	JH1-22	c	c			c	c	JH1-22	STG2_V+	IN2V+
	STG2_TMP	RED	I-	3	3								23	JH1-23	u	u			u	u	JH1-23	STG2_I-	IN2I-
	STG2_TMP	GRN	V-	4	4								24	JH1-24	DD	DD			DD	DD	JH1-24	STG2_V-	IN2V-
COLD STRUCT	CLDST_TMP	BLK/BLU	I+	1	1								17	JH2-1	n	n			n	n	JH2-1	STG2_I+	IN3+
TEMP SENSOR	CLDST_TMP	YEL/CLR	V+	2	2								18	JH2-2	U	U			U	U	JH2-2	STG2_V+	IN3V+
	CLDST_TMP	RED	I-	3	3								19	JH2-3	T	T			T	T	JH2-3	STG2_I-	IN3I-
	CLDST_TMP	GRN	V-	4	4								20	JH2-4	AA	AA			AA	AA	JH2-4	STG2_V-	IN3V-
RAD SHLD	RSHLD_TMP	BLK/BLU	I+	1	1								21	JH2-5	z	z			z	z	JH2-5	STG2_I+	IN4+
TEMP SENSOR	RSHLD_TMP	YEL/CLR	V+	2	2								22	JH2-6	m	m			m	m	JH2-6	STG2_V+	IN4V+
	RSHLD_TMP	RED	I-	3	3								23	JH2-7	k	k			k	k	JH2-7	STG2_I-	IN4I-
	RSHLD_TMP	GRN	V-	4	4								24	JH2-8	S	S			S	S	JH2-8	STG2_V-	IN4V-
RAD CCC 1ST	RSCCC_TMP	BLK/BLU	I+	1	1								9	JH2-9	GG	GG			GG	GG	JH2-9	STG2_I+	IN5+
TEMP SENSOR	RSCCC_TMP	YEL/CLR	V+	2	2								10	JH2-10	j	j			j	j	JH2-10	STG2_V+	IN5V+
	RSCCC_TMP	RED	I-	3	3								11	JH2-11	P	P			P	P	JH2-11	STG2_I-	IN5I-
	RSCCC_TMP	GRN	V-	4	4								12	JH2-12	R	R			R	R	JH2-12	STG2_V-	IN5V-
APD	RSHLD_TMP	BLK/BLU	I+	1	1								13	JH2-13	i	i			i	i	JH2-13	STG2_I+	IN6+
TEMP SENSOR	RSHLD_TMP	YEL/CLR	V+	2	2								14	JH2-14	y	y			y	y	JH2-14	STG2_V+	IN6V+
	RSHLD_TMP	RED	I-	3	3								15	JH2-15	N	N			N	N	JH2-15	STG2_I-	IN6I-
	RSHLD_TMP	GRN	V-	4	4								16	JH2-16	h	h			h	h	JH2-16	STG2_V-	IN6V-